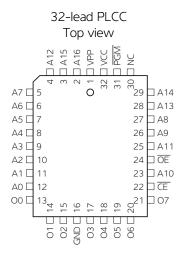


2. Pin configurations

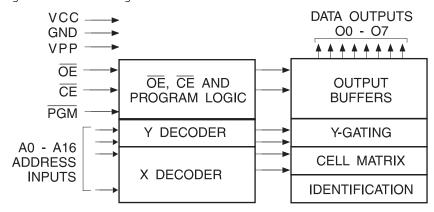
Pin name	Function
A0 - A16	Addresses
00 - 07	Outputs
Œ	Chip enable
ŌĒ	Output enable
PGM	Program strobe
NC	No connect



3. System considerations

Switching between active and standby conditions via the chip enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed datasheet limits, resulting in device nonconformance. At a minimum, a $0.1\mu\text{F}$, high-frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the V_{CC} and ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply voltage level on printed circuit boards with large EPROM arrays, a $4.7\mu\text{F}$ bulk electrolytic capacitor should be utilized, again connected between the V_{CC} and ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

Figure 3-1. Block diagram



4. Absolute maximum ratings*

Temperature under bias40°C to +85°C
Storage temperature65°C to +125°C
Voltage on any pin with respect to ground2.0V to +7.0V ⁽¹⁾
Voltage on A9 with respect to ground2.0V to +14.0V ⁽¹⁾
V_{pp} supply voltage with respect to ground2.0V to +14.0V ⁽¹⁾

*NOTICE: Stresses beyond those listed under "Absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may

affect device reliability.

Note:

1. Minimum voltage is -0.6V DC, which may undershoot to -2.0V for pulses of less than 20ns. Maximum output pin voltage is $V_{CC} + 0.75V$ DC, which may be exceeded if certain precautions are observed (consult application notes), and which may overshoot to +7.0V for pulses of less than 20ns.

5. DC and AC characteristics

Table 5-1. Operating modes

Mode/Pin	Œ	ŌĒ	PGM	Ai	V _{PP}	V _{CC}	Outputs
Read ⁽²⁾	V _{IL}	V _{IL}	X ⁽¹⁾	Ai	X	V _{CC}	D _{OUT}
Output disable ⁽²⁾	X	V _{IH}	X	X	X	V _{CC}	High Z
Standby ⁽²⁾	V _{IH}	X	X	X	X	V _{CC}	High Z
Rapid program ⁽³⁾	V _{IL}	V _{IH}	V _{IL}	Ai	V _{PP}	V _{CC}	D _{IN}
PGM verify ⁽³⁾	V _{IL}	V _{IL}	V _{IH}	Ai	V _{PP}	V _{CC}	D _{OUT}
PGM inhibit ⁽³⁾	V _{IH}	X	X	X	V_{PP}	V _{CC}	High Z
Product identification ⁽³⁾⁽⁵⁾	V _{IL}	V _{IL}	X	$A9 = V_{H}^{(4)}$ $A0 = V_{IH} \text{ or } V_{IL}$ $A1 - A16 = V_{IL}$	X	V _{CC}	Identification code

Note:

- 1. X can be V_{IL} or V_{IH} .
- 2. Read, output disable, and standby modes require 3.0V \leq V_{CC} \leq 3.6V or 4.5V \leq V_{CC} \leq 5.5V.
- 3. Refer to programming characteristics. Programming modes require $V_{CC} = 6.5V$.
- 4. $V_H = 12.0 \pm 0.5 V$.
- 5. Two identifier bytes may be selected. All Ai inputs are held low $(V_{|L})$, except A9, which is set to V_{H} , and A0, which is toggled low $(V_{|L})$ to select the manufacturer's identification byte and high $(V_{|H})$ to select the device code byte.

Table 5-2. DC and AC operating conditions for read operation

	Atmel AT27LV010A-70
Industrial operating temperature (case)	-40°C − 85°C
V. annual surah	3.0V to 3.6V
V _{CC} power supply	5V ± 10%





Table 5-3. DC and operating characteristics for read operation

Symbol	Parameter	Condition	Min	Max	Units
V _{CC} = 3.0V	to 3.6V		·		
I _{LI}	Input load current	$V_{IN} = 0V \text{ to } V_{CC}$		±1	μΑ
I _{LO}	Output leakage current	V _{OUT} = 0V to V _{CC}		±5	μA
I _{PP1} ⁽²⁾	V _{PP} ⁽¹⁾ read/standby current	$V_{PP} = V_{CC}$		10	μΑ
)/ (1) -tll	I_{SB1} (CMOS), $\overline{CE} = V_{CC\pm} 0.3V$		20	μΑ
I _{SB}	V _{CC} ⁽¹⁾ standby current	I_{SB2} (TTL), $\overline{CE} = 2.0 \text{ to } V_{CC} + 0.5V$		100	μΑ
I _{CC}	V _{CC} active current	$f = 5MHz$, $I_{OUT} = 0mA$, $\overline{CE} = V_{IL}$		8	mA
V _{IL}	Input low voltage		-0.6	0.8	V
V _{IH}	Input high voltage		2.0	V _{CC} + 0.5	V
V _{OL}	Output low voltage	I _{OL} = 2.0mA		0.4	V
V _{OH}	Output high voltage	I _{OH} = -2.0mA	2.4		V
V _{CC} = 4.5V	to 5.5V		•		
I _{LI}	Input load current	$V_{IN} = 0V \text{ to } V_{CC}$		±1	μA
I _{LO}	Output leakage current	V _{OUT} = 0V to V _{CC}		±5	μΑ
I _{PP1} ⁽²⁾	V _{PP} ⁽¹⁾ read/standby current	$V_{PP} = V_{CC}$		10	μΑ
)/ (1) -tll	I_{SB1} (CMOS), $\overline{CE} = V_{CC} \pm 0.3V$		100	μA
I _{SB}	V _{CC} ⁽¹⁾ standby current	I_{SB2} (TTL), \overline{CE} = 2.0 to V_{CC} + 0.5 V		1	mA
I _{CC}	V _{CC} active current	$f = 5MHz$, $I_{OUT} = 0mA$, $\overline{CE} = V_{IL}$		25	mA
V _{IL}	Input low voltage		-0.6	0.8	V
V _{IH}	Input high voltage		2.0	V _{CC} + 0.5	V
V _{OL}	Output low voltage	I _{OL} = 2.1mA		0.4	V
V _{OH}	Output high voltage	Ι _{ΟΗ} = -400μΑ	2.4		V

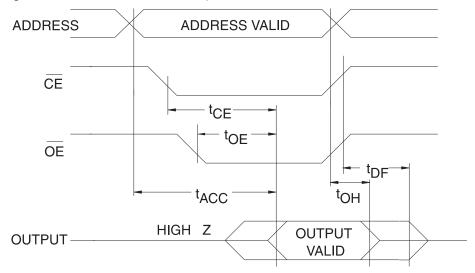
Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} , and removed simultaneously with or after V_{PP} .

Table 5-4. AC characteristics for read operation

			Atmel AT27LV010A-70		
Symbol	Parameter	Condition	Min	Max	Units
t _{ACC} (3)	Address to output delay	$\overline{CE} = \overline{OE} = V_{IL}$		70	ns
t _{CE} ⁽²⁾	CE to output delay	OE = V _{IL}		70	ns
t _{OE} ⁽²⁾⁽³⁾	OE to output delay	CE = V _{IL}		40	ns
t _{DF} ⁽⁴⁾⁽⁵⁾	OE or CE high to output float, whichever occurred first			35	ns
t _{OH}	Output hold from address, $\overline{\text{CE}}$ or $\overline{\text{OE}}$, whichever occurred first		0		ns

^{2.} V_{PP} may be connected directly to V_{CC} , except during programming. The supply current would then be the sum of I_{CC} and I_{PP} .

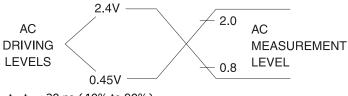
Figure 5-1. AC waveforms for read operation⁽¹⁾



Notes:

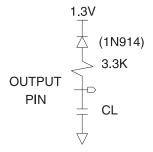
- 1. Timing measurement references are 0.8V and 2.0V. Input AC drive levels are 0.45V and 2.4V, unless otherwise specified.
- 2. \overline{OE} may be delayed up to t_{CE} t_{OE} after the falling edge of \overline{CE} without impact on t_{CE} .
- 3. $\overline{\text{OE}}$ may be delayed up to t_{ACC} t_{OE} after the address is valid without impact on t_{ACC} .
- 4. This parameter is only sampled, and is not 100% tested.
- 5. Output float is defined as the point when data is no longer driven.

Figure 5-2. Input test waveforms and measurement level



 $t_{R'}$, t_{F} < 20 ns (10% to 90%)

Figure 5-3. Output test load



Note: CL = 100pF including jig capacitance.





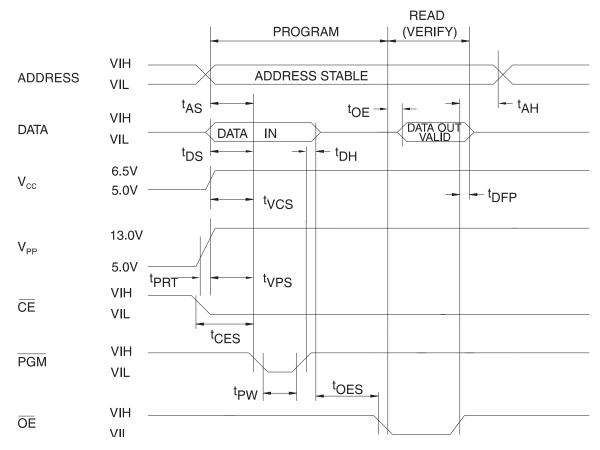
Table 5-5. Pin capacitance

 $f = 1MHz, T = 25°C^{(1)}$

Symbol	Тур	Max	Units	Conditions
C _{IN}	4	8	pF	V _{IN} = 0V
C _{OUT}	8	12	pF	V _{OUT} = 0V

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled, and is not 100% tested.

Figure 5-4. Programming waveforms⁽¹⁾



Notes:

- 1. The input timing reference is 0.8V for $\rm V_{IL}$ and 2.0V for $\rm V_{IH^*}$
- 2. t_{OE} and t_{DFP} are characteristics of the device, but must be accommodated by the programmer.
- 3. When programming the Atmel AT27LV010A, a $0.1\mu F$ capacitor is required across V_{pp} and ground to suppress spurious voltage transients.

Table 5-6. DC programming characteristics

 $T_A = 25 \pm 5$ °C, $V_{CC} = 6.5 \pm 0.25$ V, $V_{PP} = 13.0 \pm 0.25$ V

			Limits		
Symbol	Parameter	Test conditions	Min	Max	Units
I _{LI}	Input load current	$V_{IN} = V_{IL}, V_{IH}$		±10	μA
V _{IL}	Input low level		-0.6	0.8	V
V _{IH}	Input high level		2.0	V _{CC} + 0.5	V
V _{OL}	Output low voltage	I _{OL} = 2.1mA		0.4	V
V _{OH}	Output high voltage	Ι _{ΟΗ} = -400μΑ	2.4		V
I _{CC2}	V _{CC} supply current (program and verify)			40	mA
I _{PP2}	V _{PP} supply current	$\overline{CE} = \overline{PGM} = V_{IL}$		20	mA
V _{ID}	A9 product identification voltage		11.5	12.5	V

Table 5-7. AC programming characteristics

 $T_A = 25 \pm 5$ °C, $V_{CC} = 6.5 \pm 0.25$ V, $V_{PP} = 13.0 \pm 0.2$ V

			Lin			
Symbol Parameter		Test conditions ⁽¹⁾	Min	Max	Units	
t _{AS}	Address setup time		2		μs	
t _{CES}	CE setup time	Input rise and fall times	2		μs	
t _{OES}	OE setup time	Input rise and fall times (10% to 90%) 20ns Input pulse levels 0.45V to 2.4V	2		μs	
t _{DS}	Data setup time		2		μs	
t _{AH}	Address hold time		0		μs	
t _{DH}	Data hold time		2		μs	
t _{DFP}	OE high to output float delay ⁽²⁾	Input timing reference level	0	130	ns	
t _{VPS}	V _{PP} setup time	0.8V to 2.0V	2		μs	
t _{VCS}	V _{CC} setup time		2		μs	
t _{PW}	PGM program pulse width ⁽³⁾	Output timing reference level	95	105	μs	
t _{OE}	Data valid from $\overline{\text{OE}}$	0.8V to 2.0V		150	ns	
t _{PRT}	V _{PP} pulse rise time during programming		50		ns	

Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously with or after V_{PP} .

- 2. This parameter is only sampled, and is not 100% tested. Output float is defined as the point where data is no longer driven. See timing diagram.
- 3. Program pulse width tolerance is 100 μ sec \pm 5%.

Table 5-8. The Atmel AT27LV010A integrated product identification code⁽¹⁾

		Pins								
Codes	A0	07	O6	O5	04	О3	02	01	00	Hex data
Manufacturer	0	0	0	0	1	1	1	1	0	1E
Device type	1	0	0	0	0	0	1	0	1	05

Note: 1. The Atmel AT27LV010A has the same product identification code as the Atmel AT27C010. Both are programming compatible.

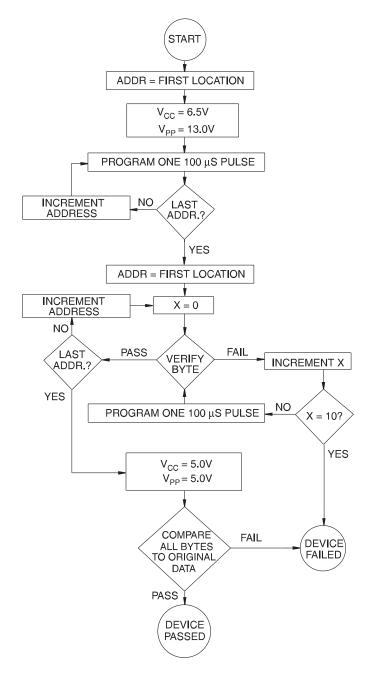




6. Rapid programming algorithm

A 100 μ s \overline{PGM} pulse width is used to program. The address is set to the first location. V_{CC} is raised to 6.5V and V_{PP} is raised to 13.0V. Each address is first programmed with one 100 μ s \overline{PGM} pulse without verification. Then a verification/reprogramming loop is executed for each address. In the event a byte fails to pass verification, up to 10 successive 100 μ s pulses are applied with a verification after each pulse. If the byte fails to verify after 10 pulses have been applied, the part is considered failed. After the byte verifies properly, the next address is selected until all have been checked. V_{PP} is then lowered to 5.0V and V_{CC} to 5.0V. All bytes are read again and compared with the original data to determine if the device passes or fails.

Figure 6-1. Rapid programming algorithm



7. Ordering information

Green package option (Pb/halide-free)

t _{ACC}		mA) : 3.6V				
(ns)	Active	Standby	Atmel ordering code	Package	Lead finish	Operation range
70	8	0.02	AT27LV010A-70JU	32J	Matte tin	Industrial (-40°C to 85°C)

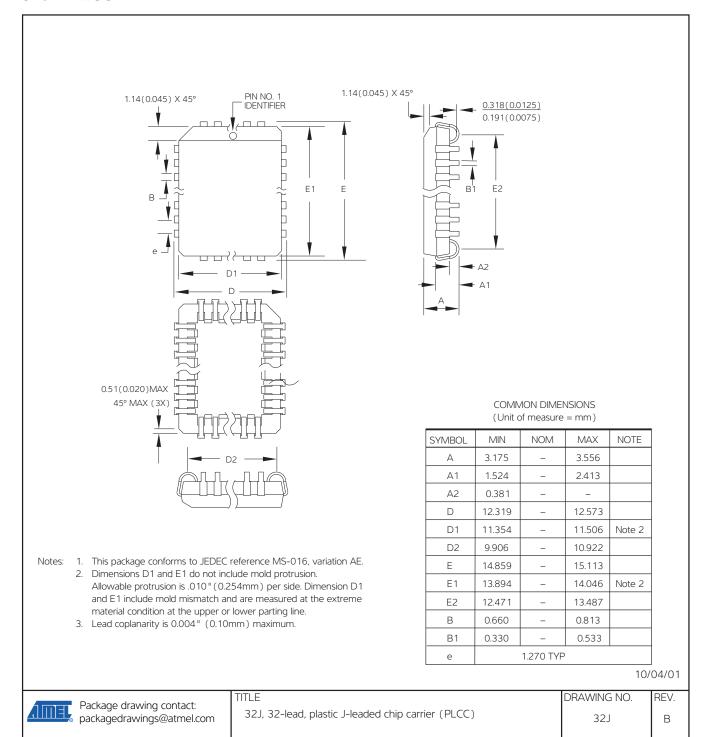
	Package type
32J	32-lead, plastic, J-leaded chip carrier (PLCC)





8. Packaging Information

32J – PLCC



9. Revision history

Doc. rev.	Date	Comments
0548F	04/2011	Remove TSOP and VSOP packages Add lead finish to ordering information
0548E	12/2007	And read in its in to ordering information





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